Materials Declaration

Package	TQFP - EP
Body Size	12 X 12 X 1.0 (6.0 mm ep)
LeadCount	80
Option	Pb-Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	88	2.11 E-01	556661
Multi-aromatic Resin	11.5	2.75 E-02	72746
Carbon Black	0.5	1.20 E-03	3163
Subtotal		2.39 E-01	632570

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	99.25	1.07 E-01	282236
Cr	0.3	3.23 E-04	854
Sn	0.25	2.69 E-04	711
Zn	0.2	2.15 E-04	568
Subtotal		1.08 E-01	284369

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	9.60 E-04	2537

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	7.37 E-03	19474

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.66 E-03	4395

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.74 E-02	46094

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	70	2.80 E-03	7392
Resin	20	7.99 E-04	2112
Anhydride	10	4.00 E-04	1057
Subtotal		4.00 E-03	10560

Molding Compound

Item	PPM	Method
Pb	None Detected	USEPA 3052. ICP-AES.
Cd	None Detected	USEPA 3052. ICP-AES.
Hg	None Detected	USEPA 3052. ICP-AES
Cr+6	None Detected	USEPA 3060A & 7196A.
PBB	None Detected	USEPA 8081A/8270D/3540C or 3550C. GC/MS.
PBDE	None Detected	USEPA 8081A/8270D/3540C or 3550C. GC/MS.

Die Attach Paste

Item	PPM	Method
Pb	None Detected	EPA Method 3051A/3052. ICP-OES.
Cd	None Detected	EPA Method 3051A/3052. ICP-OES.
Hg	None Detected	EPA Method 3051A/3052. ICP-OES.
Cr+6	None Detected	EPA Method 3060A & 7196A. UV-VIS.
PBB	None Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	None Detected	EPA Method 3540C/3550C. GC/MS.

Package Totals

Weight (g)	PPM
3.78 E-01	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ADI Proprietary

Materials Declaration

Package	TQFP - EP
Body Size	12 X 12 X 1.0 (6.0 mm ep)
LeadCount	80
Option	SnPb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	88	2.08 E-01	546110
Multi-aromatic Resin	11.5	2.71 E-02	71367
Carbon Black	0.5	1.18 E-03	3103
Subtotal		2.36 E-01	620580

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	99.25	1.07 E-01	280823
Cr	0.3	3.23 E-04	849
Sn	0.25	2.69 E-04	707
Zn	0.2	2.15 E-04	565
Subtotal		1.08 E-01	282945

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	9.60 E-04	2524

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	6.78 E-03	17825
Pb	15	1.20 E-03	3145
Subtotal		7.98 E-03	20970

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.66 E-03	4373

Chip

	% of Chip	Weight (g)	PPM
Si	100	2.16 E-02	56723

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	70	3.16 E-03	8320
Resin	20	9.04 E-04	2377
Anhydride	10	4.52 E-04	1189
Subtotal		4.52 E-03	11885

Molding Compound

Item	PPM	Method
Pb	None Detected	USEPA 3052. ICP-AES.
Cd	None Detected	USEPA 3052. ICP-AES.
Hg	None Detected	USEPA 3052. ICP-AES
Cr+6	None Detected	USEPA 3060A & 7196A.
PBB	None Detected	USEPA 8081A/8270D/3540C or 3550C. GC/MS.
PBDE	None Detected	USEPA 8081A/8270D/3540C or 3550C. GC/MS.

Die Attach Paste

Item	PPM	Method
Pb	None Detected	EPA Method 3051A/3052. ICP-OES.
Cd	None Detected	EPA Method 3051A/3052. ICP-OES.
Hg	None Detected	EPA Method 3051A/3052. ICP-OES.
Cr+6	None Detected	EPA Method 3060A & 7196A. UV-VIS.
PBB	None Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	None Detected	EPA Method 3540C/3550C. GC/MS.

Package Totals

Weight (g)	PPM
3.80 E-01	1000000

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